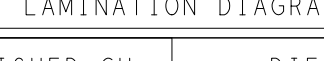


REVISIONS			
REV	DESCRIPTION	APPROVED	DATE
P1	INITIAL RELEASE	DP/PR	10/06/15
P2	REVISION RELEASE	DM	12/01/15
A	PRODUCTION RELEASE	DM	09/01/16

NOTES: UNLESS OTHERWISE SPECIFIED  
 1. DIMENSIONS ARE IN INCHES (EXCEPT WHERE NOTED).  
 MATERIAL: (USE CHECKED ITEMS FOR MATERIAL)  
 2. BOARD MATERIAL:  
 (X) ISOLA 370HR OR EQUIVALENT  
 ( ) ISOLA-FR408HR OR EQUIVALENT  
 ( ) NELCO-4000-13  
 ( ) MEGTRON 6  
 ( ) ROGERS 4350B  
 ( ) ROGERS 4003C  
 ( ) OTHER \_\_\_\_\_  
 3. THE PCB SHALL BE FABRICATED TO IPC-6012, TYPE X, CLASS 2.  
 WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2, CURRENT REVISIONS.  
 4. BOARD MATERIAL & CONSTRUCTION SHALL MEET THE REQUIREMENTS OF UL796  
 WITH FLAMMABILITY RATING OF 94V-0.  
 5. OVERALL BOARD THICKNESS REFER TO LAMINATION DIAGRAM. TOLERANCE APPLIES  
 AFTER ALL LAMINATION AND PLATING PROCESSES. IT IS TO BE MEASURED FROM  
 TOP PCB METAL TO BOTTOM PCB METAL UNLESS OTHERWISE SPECIFIED.  
 6. BOW & TWIST NOT TO EXCEED 0.0075 IN. (0.75%) PER LINEAR INCH.  
 BOW & TWIST SHOULD BE MEASURED PER IPC-TM-650, METHOD 2.4.22.  
 TOOLING: (USE CHECKED ITEMS FOR TOOLING)  
 7. PHOTO ETCH CIRCUITRY PER ENCLOSED GERBER R9274X OR D98-- FORMAT FILE,  
 DRILL LOCATION AND SIZE CONTROLLED BY EXCELLON CBN ORILL FILE.  
 8. IF STATED IN THE LAMINATION DIAGRAM, THE DIELECTRIC THICKNESS OF ANY  
 CONTROLLED IMPEDANCE LAYER IS FOR REFERENCE ONLY. FINAL ACCEPTANCE  
 SHALL BE DETERMINED BY THESE LAYERS HAVING A CHARACTERISTIC  
 IMPEDANCE OF +/-10% OHMS AS STATED IN THE LAMINATION DIAGRAM. THE  
 VENDOR CAN MAKE ADJUSTMENTS AS LONG AS THE STATED IMPEDANCE AND  
 OVERALL BOARD THICKNESS IS MAINTAINED. ANY ADJUSTMENT MADE TO TRACE  
 WIDTH OR SPACING MUST HAVE PRIOR WRITTEN APPROVAL FROM MAXIM.  
 9. ALL TRACES FILLETED OPTION TO ENHANCE RELIABILITY AT PAD JUNCTIONS  
 WHERE SPACING PERMITS. UNLESS OTHERWISE SPECIFIED:  
 ( ) FILLETED  
 (X) NOT FILLETED  
 10. LAYER TO LAYER REGISTRATIONS SHALL BE WITHIN .003 INCHES.  
 LEGEND TO LEGEND +/- 0.007 INCHES  
 FINISH: (USE CHECKED ITEMS FOR PLATING)  
 11. PLATING SPECIFICATION:  
 (X) STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (1 OZ). THE FINISH COPPER WEIGHT IS (1 OZ).  
 FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (1 OZ) AS A STARTING WEIGHT  
 THE STARTING WEIGHT CAN BE (0.5 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (1 OZ)  
 UNLESS OTHERWISE SPECIFIED  
 ( ) STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (1 OZ). THE FINISH COPPER WEIGHT IS (2 OZ).  
 FOR OUTER LAYER WHERE SPACING PREVENTS THE USE OF (1 OZ) AS A STARTING WEIGHT,  
 THE STARTING WEIGHT CAN BE (0.5 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (2 OZ).  
 UNLESS OTHERWISE SPECIFIED  
 ( ) STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (2 OZ). THE FINISH COPPER WEIGHT IS (2 OZ) MINIMUM  
 FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (2 OZ) AS A STARTING WEIGHT,  
 THE STARTING WEIGHT CAN BE (2 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (2 OZ).  
 UNLESS OTHERWISE SPECIFIED  
 ( ) OTHER \_\_\_\_\_  
 12. CHECK ALL THAT APPLY  
 ( ) ELECTRODEPOSITED HARD GOLD PLATE, TYPE 1 (99.7% MIN GOLD), GRADE C  
 (KNOPF HARDNESS 130-200), CLASS 1 (50-100 MICRO INCHES THICK) IN ACCORDANCE WITH MIL-G-45204  
 GENERAL SURFACE REQUIREMENTS MUST MEET ANSI/IPC-A-600(CURRENT REV) SECTION 4.0.  
 CLASS 3 (50-100 MICRO INCHES THICK) OVER ELECTRODEPOSITED NICKEL PLATE  
 IN ACCORDANCE WITH ANSI/IPC-A-6000, SECTION 4.0, CLASS 3 (200-400 MICROINCHES THICK).  
 (X) FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 3-8 MICRO INCHES OVER  
 100 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL.  
 ( ) FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 2-5 MICRO INCHES OVER  
 118-236 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL.  
 ( ) FINGERS TO BE GOLD PLATED.  
 ( ) LEAD FREE AND RoHS COMPLIANT PLATING.  
 ( ) OTHER \_\_\_\_\_  
 13. DRILL SIZES ARE FINISHED HOLE SIZES. ALL HOLES SHALL BE LOCATED WITHIN .005 DTP.  
 MINIMUM BARREL PLATING OF .001 IN. PLATED HOLES SHALL NOT BE ROUGH OR IRREGULAR  
 SO AS TO HINDER PROPER SOLDER WICKING.  
 14. CHECK ALL THAT APPLY  
 (X) GREEN SOLDERMASK OVER BARE COPPER/BARE GOLD (BOTH SIDES) WITH LIQUID PHOTO IMAGEABLE INK (LPI)  
 PER ARTWORK  
 ( ) GREEN TAYLO PSR-4000  
 ( ) OTHER \_\_\_\_\_  
 15. CHECK ALL THAT APPLY  
 (X) APPLY SILKSCREEN USING A NON-CONDUCTIVE, WHITE EPOXY  
 BASED INK PER ARTWORK.  
 ( ) OTHER \_\_\_\_\_  
 16. VENDOR LOGO & DATE CODE REQUIRED IN INK ON BOTTOM SIDE ONLY. DATE CODE FORMAT MUST BE YYYY ONLY.  
 TESTING:  
 17. FINAL ELECTRICAL TEST TO BE PERFORMED USING PROVIDED IPC-D-356A NETLIST OR ODB++ FORMAT FILE.  
 (REQUIRED UNLESS OTHERWISE SPECIFIED IN QUOTE)  
 THE PCB SHALL HAVE A VERIFICATION STAMP.  
 18. A TIME DOMAIN REFLECTOMETER REPORT FOR EACH IMPEDANCE CONTROLLED LAYER AND A CERTIFICATE  
 OF COMPLIANCE SHALL BE PROVIDED BY VENDOR AT TIME OF SHIPMENT. INSTANCES WHERE TOR TESTING  
 CAN'T BE PERFORMED BECAUSE THE TRACE LENGTH IS TOO SHORT ON THE OUTER LAYERS AT THE PIN ESCAPES  
 IS ACCEPTABLE. ALL OTHER INSTANCES MUST BE REPORTED.  
 MISCELLANEOUS:  
 19. IF PRESENT, ALL BLIND/BURIED VIAS WITH AN ASPECT RATIO <:1 TO BE PLATED SHOT WITH COPPER WHEN  
 USED AS VIA-IN-PAD OR AS A STACKED VIA. BLIND/BURIED VIAS WITH AN ASPECT RATIO >:1 TO BE FILLED  
 WITH NON-CONDUCTIVE EPOXY, UNLESS OTHERWISE SPECIFIED.  
 20. FOR ALL DRILL INFORMATION REFER TO DRILL CHART.  
 ( ) NON-CONDUCTIVE EPOXY. FILL AND CAP ALL 0.0XXX INCH DRILLED VIAS.  
 ( ) SILVER. FILL AND CAP ALL 0.0XXX INCH DRILLED VIAS.  
 21. FINISHED SURFACE CONTACTS AND FILLED VIAS TO BE FREE OF ANY PITS, SCRATCHES PROBE MARKS  
 OR OTHER DEFECTS THAT COULD EFFECT THE APPEARANCE AND PERFORMANCE OF THE CONTACT  
 SURFACE. CONTACTS ARE TO BE AS FLAT AS POSSIBLE. NOT TO EXCEED +/- 0.001" OF FLATNESS.  
 22. THIEVING:  
 ( ) SUPPLIER MAY ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.  
 (X) SUPPLIER MAY NOT ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.  
 23. PENMUT  
 ( ) PENMUTS TO BE INSTALLED BY SUPPLIER.  
 ( ) PENMUTS NOT TO BE INSTALLED BY SUPPLIER.  
 (X) NOT APPLICABLE

LAMINATION DIAGRAM				
LAYER NUMBER	LAYER NAME	FINISHED CU WEIGHT (oz)	DIELECTRIC THICKNESS (in.)	DIELECTRIC MATERIAL
1	TOP	1		FOIL
2	BOTTOM	1		TBD
THE FINISHED PCB THICKNESS TO BE: 0.0625" +/- 0.010"				

DRILL CHART: TOP to BOTTOM					
ALL UNITS ARE IN MILS					
FIGURE	SIZE	TOLERANCE	PLATED	QTY	NOTES
△	12.0	+3.0/-10.0	PLATED	8	
⑩	27.56	+3.0/-3.0	PLATED	3	
⑪	39.37	+3.0/-3.0	PLATED	16	
⑫	125.0	+3.0/-3.0	PLATED	4	

**maxim integrated.**

MAXIM INTEGRATED PRODUCTS, INC. 1201 SAN JUAN AVENUE, SEVENTH FLOOR, SAN JOSE, CA 95128-6299, U.S.A.  
 TEL: 408/737-0600 FAX: 408/737-0699 E-MAIL: MAXIM@MAXIM-IC.COM

HWIDFNAME: NAME=96031575TR\_SW17\_A


HWIDFNAME NUMBER: \_\_\_\_\_

DESIGNATOR: M4

DATE: 04/01/2006 IDB+SERIES: FAB\_NOTES

1.63

1.90

TOLERANCES UNLESS OTHERWISE SPECIFIED		THE INFORMATION CONTAINED IN THIS DOCUMENT IS PROPRIETARY TO MAXIM. THE INFORMATION IN THIS DOCUMENT IS NOT TO BE SHOWN, REPRODUCED, OR DISCLOSED TO ANYONE OUTSIDE OF MAXIM WITHOUT PRIOR WRITTEN PERMISSION FROM MAXIM.		 <b>maxim integrated™</b>	
FRACTIONS      DECIMALS      ANGLES $\frac{.}{.} \text{ } \frac{.}{.} \text{ } \frac{.}{.}$ .XX ./. .01      ./. $\frac{.}{.}$ $\frac{.}{.}$ .XXX ./. .005				HARDWARE NAME :	
MATERIAL:		DRAWN BY: MANIKANDAN S      DATE: 08/31/2016		MAX17572B_EVKIT_A	
SEE NOTES		CHECKED BY: DIPANKAR M      DATE: 09/01/2016		HARDWARE NUMBER:	
FINISH:		APPR. BY: DIPANKAR M      DATE: 09/01/2016		XX - XXXXX - XXX	
SEE NOTES		APPR. BY:      DATE:		NOT TO SCALE      TEMPLATE REV:	
				SHEET 1 OF	
				A	